

ABSTRACT

This project studies the surface morphology of the copper deposit from three different bath solutions on polished copper (3.1 mm in diameter) electrode by using Scanning Electron Microscopy. The behaviour of glycine as an additive in a bath solution containing 0.3 M of copper (II) sulphate and 2.2 M of sulphuric acid was studied by using cyclic voltammetry. In this project, glycine did not involved directly in the reaction of Cu^{2+}/Cu couple but increased the potential and current density of the plating process. However, glycine has the properties for inhibiting the deposition of copper onto the copper disc. Moreover, block growth and nodules growth is observed on the surface of the copper disc.